

OPEN

Compute Project

Project Olympus Rack Manager Specification

Author:

Mark A. Shaw, Principal Hardware Engineering Manager, Microsoft

Revision History

Date	Description
2/15/2017	Version 1.0

Open Compute Project • Project Olympus Rack Manager Specification

© 2017 Microsoft Corporation.

As of February 15, 2017, the following persons or entities have made this Specification available under the Open Web Foundation Final Specification Agreement (OWFa 1.0), which is available at <http://www.openwebfoundation.org/legal/the-owf-1-0-agreements/owfa-1-0>

Microsoft Corporation.

You can review the signed copies of the Open Web Foundation Agreement Version 1.0 for this Specification at <http://opencompute.org/licensing/>, which may also include additional parties to those listed above.

Your use of this Specification may be subject to other third party rights. THIS SPECIFICATION IS PROVIDED "AS IS." The contributors expressly disclaim any warranties (express, implied, or otherwise), including implied warranties of merchantability, non-infringement, fitness for a particular purpose, or title, related to the Specification. The entire risk as to implementing or otherwise using the Specification is assumed by the Specification implementer and user. IN NO EVENT WILL ANY PARTY BE LIABLE TO ANY OTHER PARTY FOR LOST PROFITS OR ANY FORM OF INDIRECT, SPECIAL, INCIDENTAL, OR CONSEQUENTIAL DAMAGES OF ANY CHARACTER FROM ANY CAUSES OF ACTION OF ANY KIND WITH RESPECT TO THIS SPECIFICATION OR ITS GOVERNING AGREEMENT, WHETHER BASED ON BREACH OF CONTRACT, TORT (INCLUDING NEGLIGENCE), OR OTHERWISE, AND WHETHER OR NOT THE OTHER PARTY HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGE.

CONTRIBUTORS AND LICENSORS OF THIS SPECIFICATION MAY HAVE MENTIONED CERTAIN TECHNOLOGIES THAT ARE MERELY REFERENCED WITHIN THIS SPECIFICATION AND NOT LICENSED UNDER THE OWF CLA OR OWFa. THE FOLLOWING IS A LIST OF MERELY REFERENCED TECHNOLOGY: INTELLIGENT PLATFORM MANAGEMENT INTERFACE (IPMI), I²C TRADEMARK OF PHILLIPS SEMICONDUCTOR. IMPLEMENTATION OF THESE TECHNOLOGIES MAY BE SUBJECT TO THEIR OWN LEGAL TERMS.

Table of Contents

1	Overview	4
2	Block Diagram	4
3	Features	5
3.1	ARM Processor	5
3.1.1	Boot Order (SYSBOOT)	7
3.2	DDR3L Memory	8
3.3	NOR Flash	8
3.4	eMMC Memory	8
3.5	Reset	8
3.6	Clocks	9
3.7	I2C	9
3.8	FRU EEPROM	10
3.9	Real Time Clock	10
3.10	LEDs	10
3.10.1	Power LED	10
3.10.2	Attention LED	11
3.10.3	Status LEDs	11
3.11	Blade Control	11
3.11.1	Blade Presence	11
3.11.2	Blade Enable	11
3.11.3	Blade Throttle	11
3.11.4	LR Select	12
3.12	AC Monitor	12
3.13	Remote Recovery	12
3.13.1	Remote Bootstrap	13
3.13.2	Remote Rack Manager ON/OFF	13
3.13.3	Remote Throttle	13
3.13.4	Rack Manager Present	13
3.14	Remote AC Power Control	13
3.15	PCB Revision	13
3.16	Board Interface ID	14
3.17	AM4376 GPIO Summary	14
3.18	I2C Expander (PCA9535)	15

3.19	<i>UARTS</i>	15
3.20	<i>Power</i>	15
3.20.1	Power Subsystem	15
3.20.2	Power-up/down Sequence	16
3.20.3	Grounding and Return.....	18
3.20.4	AC-DC Power Monitoring	18
3.21	<i>Stackup</i>	18
4	Connectors	19
4.1	<i>PCIe x16 Goldfinger</i>	19
4.2	<i>PCIe x8 Goldfinger</i>	24
4.3	<i>RJ45 GbE Connectors</i>	26
4.4	<i>I2C Debug Header</i>	27
5	Mechanical Specifications	27
5.1	<i>Mechanical Dimensions</i>	27
5.2	<i>Thermal</i>	28

List of Figures

Figure 1. Rack Manager 3D	4
Figure 2. Top Level Block Diagram	5
Figure 3. AM4376 Block Diagram.....	7
Figure 4. Reset Block Diagram	9
Figure 5. I2C Block Diagram	10
Figure 6. Throttle Block Diagram	12
Figure 7. Power Block Diagram	16
Figure 8. Power Up Sequence Diagram	17
Figure 9. Power Supply Slew Rate Diagram	18
Figure 10. PCB Stackup	19
Figure 11. Mechanical Dimensions	27

List of Tables

Table 1. LED Assignments	10
Table 2. PCB Revision ID.....	13
Table 3. Board Interface ID	14
Table 4. AM4376 GPIO Assignments	14
Table 5. PCA9535 I/O Assignments.....	15
Table 6. PCIe x16 Pinout	19
Table 7. PCIe x8 Pinout	24
Table 8. RJ45 GbE Pinout	26

1 Overview

The M2010 Rack Manager is an ARM processor based board for enabling management of Server Blades and a WCS Rack. It is designed to act as a hot swappable plug in module for a WCS Power and Management Distribution Unit (PMDU) or as part of a separate Rack Management Module for supporting Non WCS racks.

A 3D drawing of the Rack Manager is shown in Figure 1.

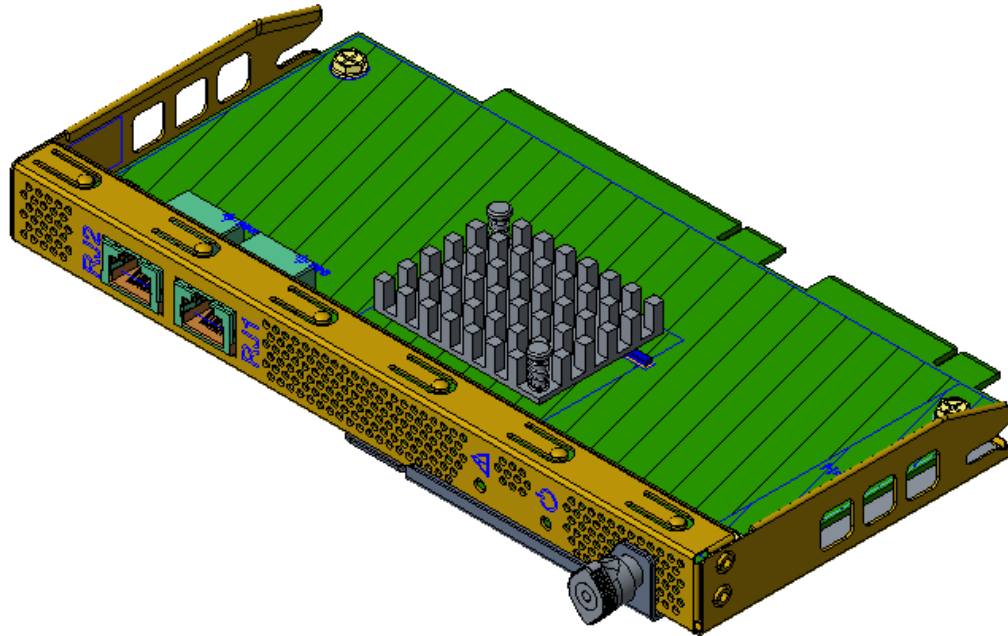


Figure 1. Rack Manager 3D

2 Block Diagram

The Rack Manager supports the following primary functional features:

- TI AM4376 ARM Processor
- 2x 1GbE for communication with Data Center and Server Blade management
- 2x UARTs for communication with Data Center Digi and Ethernet Management Switch. 1x Spare UART for Debug or future feature
- Control Signals for power control of blade slots
- Rack AC power monitoring
- Remote AC power control for Rack AC devices
- Remote On/Off control Bootstrap and RM Throttle from Row Manager in MOR
- PCIe x16 and PCIe x8 edge finger connectors for interfacing to the PMDU or other backplanes.

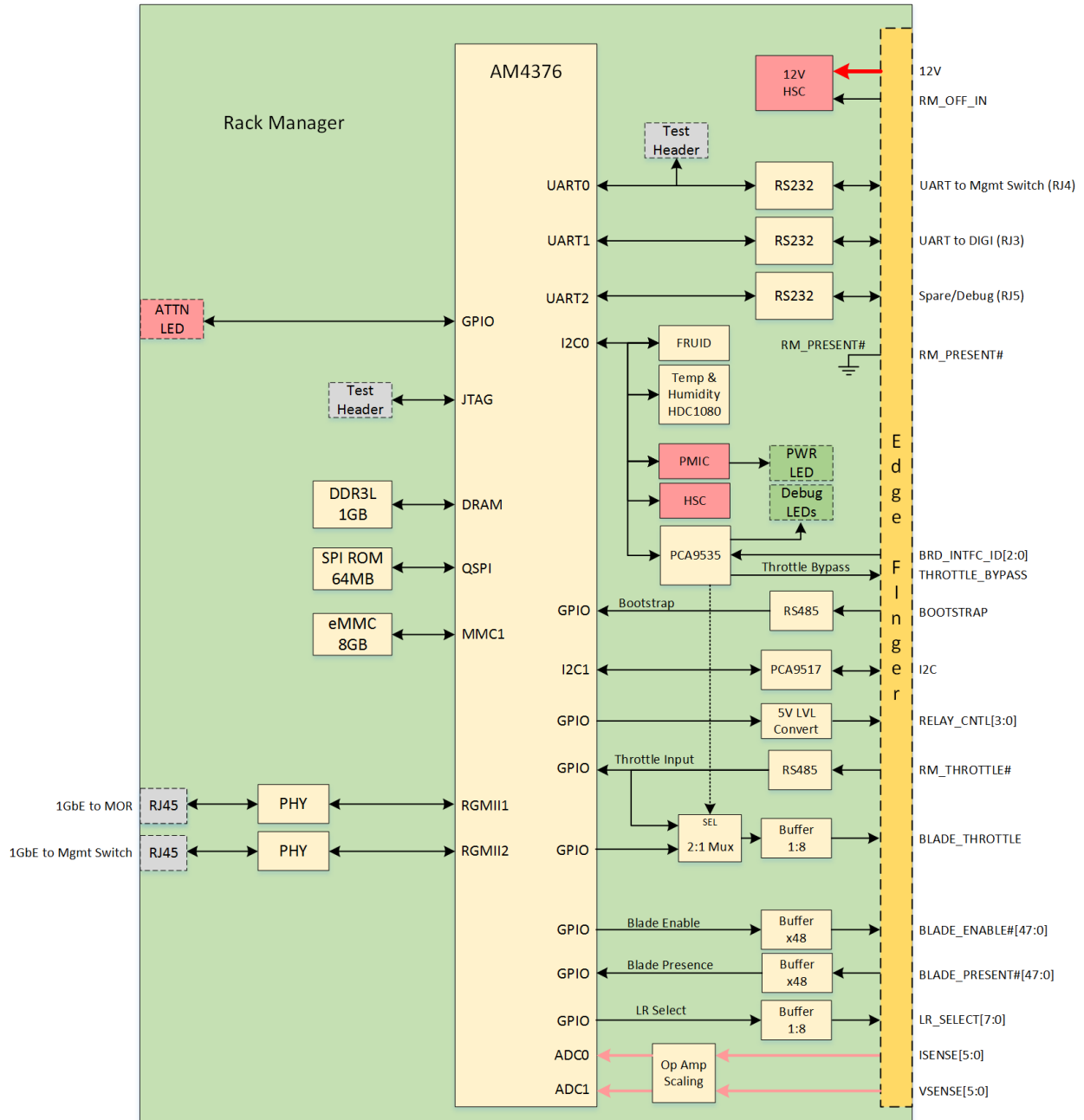


Figure 2. Top Level Block Diagram

3 Features

3.1 ARM Processor

The Rack Manager shall incorporate the Texas Instruments Sitara ARM Cortex-A9 processor AM4376. A list of key features is shown below. A functional block diagram of the process is shown in Figure 3.



- 32-bit RISC Processor with processing speed up to 1GHz
- 32-bit LPDDR2 (266MHz clock, LPDDR2-533 Data Rate), DDR3, and DDR3L (400MHz clock, DDR3-800 Data Rate) support up to 2GB
- General Purpose Memory Support NAND, NOR, SRAM. GPMC supports up to 512MB address capability with up to 16-bit ECC
- Up to two Programmable Real-Time Unit Subsystem and Industrial Communication Subsystem (PRU-ICSS) with two PRU cores each which is 32-bit RISC processor capable of running at 200MHz
- Internal 32.768-kHz Oscillator, RTC Logic, and 1.1V internal LDO
- Two Gigabit Ethernet MAC (10, 100 and 1000 Ethernet) with integrated switch
- Two Controller Area Network (CAN) ports, six UARTs, two McASPs, five McSPIs (Multichannel Serial Interface Ports up to 48MHz), three I2C ports (master and slave up to 400KHz), one QSPI (up to 48MHz) and one HDQ or 1-wire
- Support Crypto Hardware Accelerators (AES, SHA, RNG, DES and 3DES) and Secure Boot
- Two 12-bit successive Approximation Register(SAR) ADCs, 867K samples per second
- Up to six enhanced high resolution PWM modules
- Up to six banks of General Purpose I/O (GPIO), 32 GPIOs per bank
- 0.65mm ball pitch 491 pin BGA package 17mmx17mm

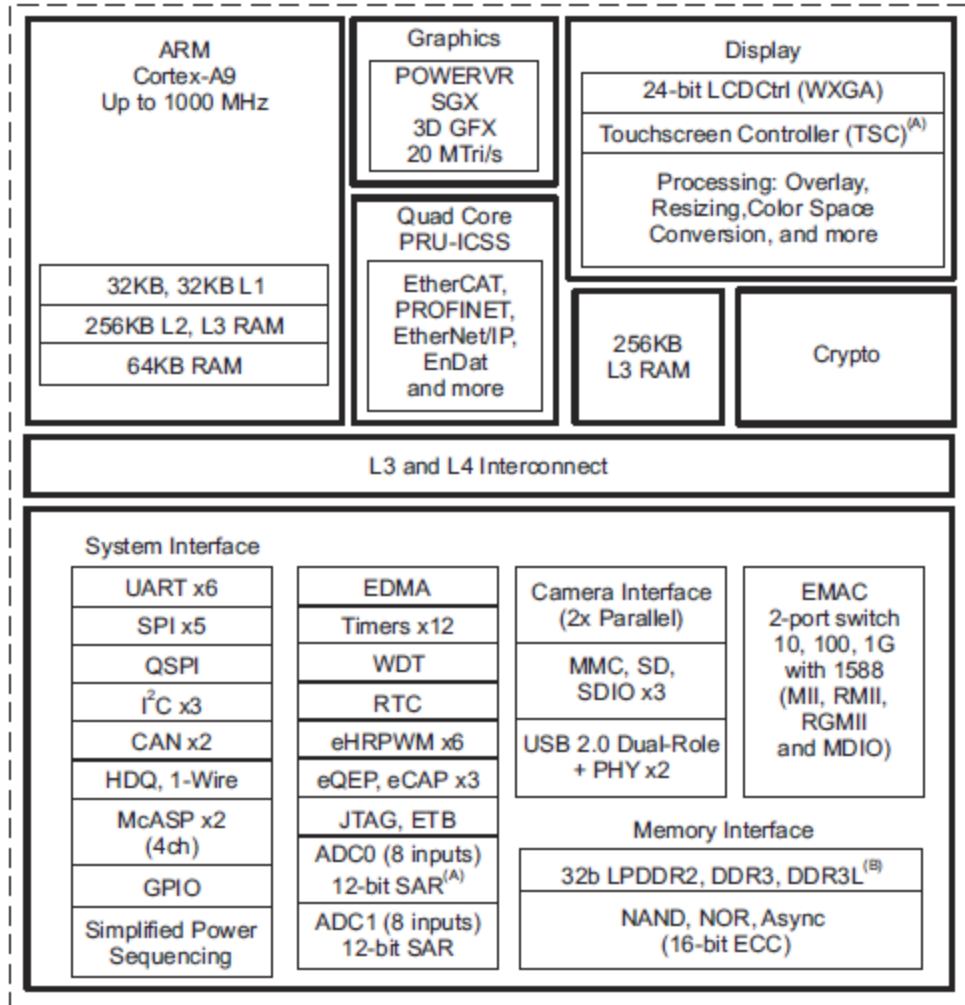


Figure 3. AM4376 Block Diagram

3.1.1 Boot Order (SYSBOOT)

The RM shall strap the SYSBOOT pins to enable the following boot order. To enable this, the SYSBOOT[4:0] inputs should be set to 11010b.

1. QSPI
2. eMMC1

The RM shall support a BOOTSTRAP input that when set should enable the following boot order. The board shall contain logic to change SYSBOOT[4:0] to 11100b when the BOOTSTRAP signal is asserted.

1. EMAC1 (network)

3.2 DDR3L Memory

The board shall support 1GB of DDR3L Memory. The memory is organized as x32 with two 32M x16 x8 banks DRAM.

3.3 NOR Flash

The Rack manager shall support 64MB of QSPI NOR Flash. The memory shall utilize QSPI mode running at 48Mhz.

3.4 eMMC Memory

The Rack Manager shall support a minimum of 1 GB of eMMC Memory.

3.5 Reset

The Rach Manager shall support two hardware resets.

- Power On Reset to AM4376 - This is driven from the power good signal of the power regulator on the Rack Manger board.
- Watchdog Reset – This is asserted to force a reset of AM4376 when the processor is locked up.

The sequence shall ensure that the output buffers remain disabled until they are enabled as part of the boot process. The circuit also supports override of the BOOTSTAP[2:1] pins to enable altering the boot device.

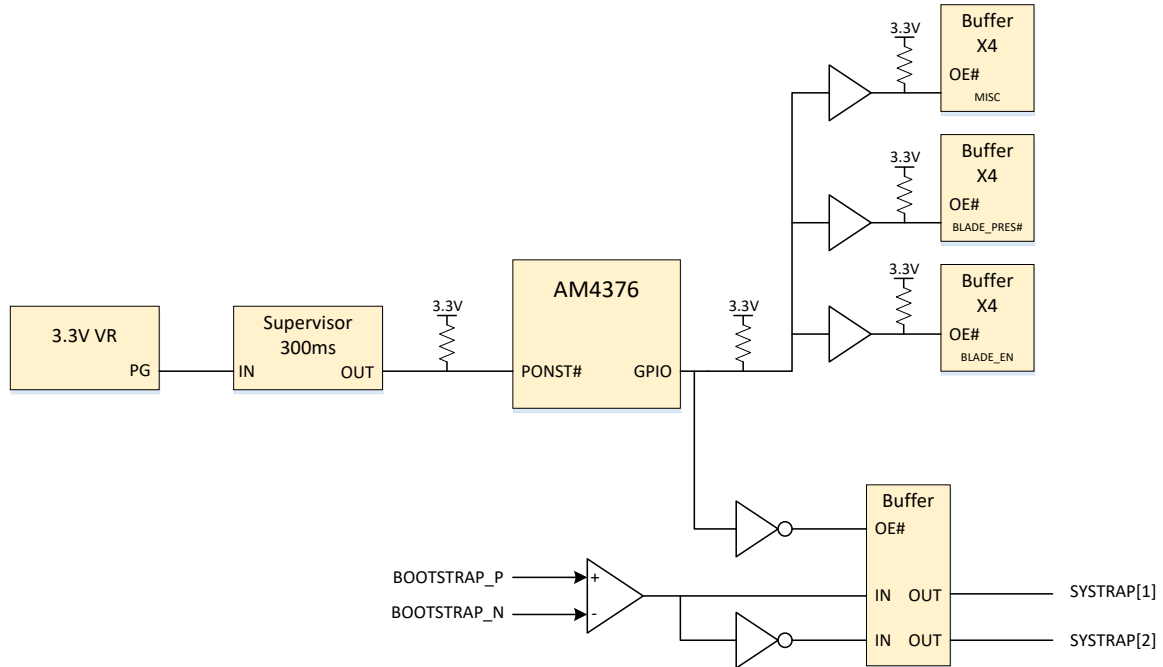


Figure 4. Reset Block Diagram

3.6 Clocks

The main clock for the processor is derived from a 24-MHz crystal. The AM4376 generates the base clock and subsequent module clocks as needed within the AM4376 processor. A 32-kHz clock for the RTC on the AM4376 is derived from a 32.768-kHz crystal on the board. A 25-MHz crystal is usually required for the clock input of Ethernet PHY

3.7 I2C

The Rack Manager shall support two I2C ports sourced from the I2C0 and I2C1 masters in the AM4376. A block diagram of the I2C tree is shown in Figure 5. I2C0 is used to communicate with components located on the Rack Manager. I2C1 is used to communicate with components located off the Rack Manager. The diagram assumes that the Rack Manager is in a standard PMDU configuration showing the FRUID addresses for the PIB and AC-DC Boards. Note that addresses shown are 8-bit address with the R/W bit as the LSB set to 0 (0x48=0100100x). All I2C ports shall support 100Khz operation.

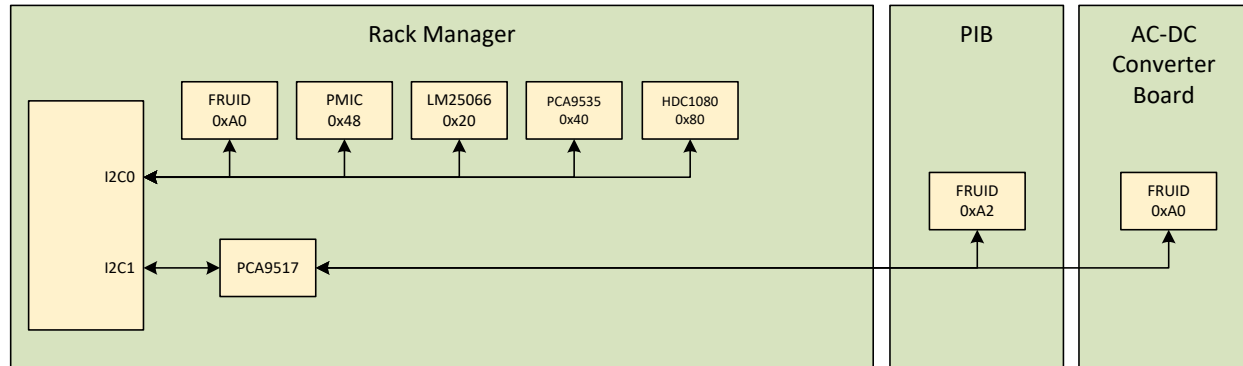


Figure 5. I2C Block Diagram

3.8 FRU EEPROM

The Rack Manager shall support a 64Kb FRUID EEPROM for storage of manufacturing data. The device shall be M24128-BWMN6TP or equivalent. Data in the EEPROM will be configured as an IPMI FRU device and fields are defined in the FRU ID Specification for the Rack Manager.

3.9 Real Time Clock

The Rack Manager shall support a CR2032 for the real-time clock contained in the AM4376 processor. The battery contains sufficient energy to power the RTC circuitry for a nominal lifetime of 7.5 years.

3.10 LEDs

The design shall contain the following LEDs to indicate functional status. The LEDs are listed in Table 1

Table 1. LED Assignments

LED Name	REF Des	Color	Description
Power LED	LED6	Green	Indicates all Power Rails are Good
Attention	LED5	Amber	Indicates that a fault has occurred
LED[3:0]	LED[4:1]	Green	Status LEDs

3.10.1 Power LED

The Power LED indicates that all the power rails on the Rack Manager are good. The LED shall be visible on the front bulkhead of the assembly.

3.10.2 Attention LED

The Attention LED indicates that a fault has been detected on the Rack Manager. The LED shall be controlled by GPIO on the AM4376 and shall be visible on the front bulkhead of the assembly.

3.10.3 Status LEDs

The Rack Manager shall support four LEDs to communicate status and debug information. The LEDs shall be driven by GPIOs on the PCA9535. The LEDs shall reside on the PCBA, but are not required to be visible on the bulkhead of the assembly. Functionality is not specified and is subject to change to support development and debug activities.

3.11 Blade Control

The Rack Manager shall support I/O for managing the power state of the blade slots. Description of the signals is given below.

3.11.1 Blade Presence

The Rack Manager shall support an active low `BLADE_PRESEN#` inputs from each of the 48 blade slots for determining the physical presence of a blade within a given slot. The signals shall be available on the GPIOs of the processor. This signal is pulled low to ground through a low impedance resistor on the blade. It should be buffered and pulled high through a high impedance pullup to isolate the Rack Manager from the blade.

3.11.2 Blade Enable

The Rack Manager shall support an active low `BLADE_EN#` output to each of the 48 blade slots for controlling the power state of the blade PSU. The signals shall be available on the GPIOs of the processor. The signal is pulled low to ground on the blade through a 1k resistor to set PSU on as the default state. The Rack Manager shall buffer the signal to isolate the Rack Manager from the blade. The design shall ensure that during hot plug insertion or removal of the Rack Manager, Blade Enable signals shall not be driven high and cause an inadvertent power disable of the blades.

3.11.3 Blade Throttle

The Rack Manager shall support throttle control output to each of the 48 blade slots for enabling control of the power throttling function on the blade. The throttle is controlled by the processor based on the `RM_THROTTLE#` input and the AC Power Monitor function. The processor shall drive a single GPIO for throttle. The board shall contain a buffer to fan out 8 throttle signals to the PMDU. The Rack Manager shall buffer the signal to isolate the Rack Manager from the blade. The design shall ensure that during hot plug insertion or removal of the Rack Manager, `BLADE_THROTTLE` signals shall not be driven high and cause inadvertent power throttling of the blades.

The board shall contain external logic to enable bypassing of the throttle logic as shown in Figure 6. The bypass (`LOCAL_BYPASS`) is controlled by an I2C GPIO to ensure that the bypass and buffer OE states are

maintained during boot cycle events. The board shall also support a separate bypass signal (THROTTLE_BYPASS) for enabling throttle bypass circuitry located externally on the ROW PIB when this board is used as part of the Stand-Alone Rack Manager. Both of these signals are pulled down on the PCB so that the default state of the board has bypass disabled.

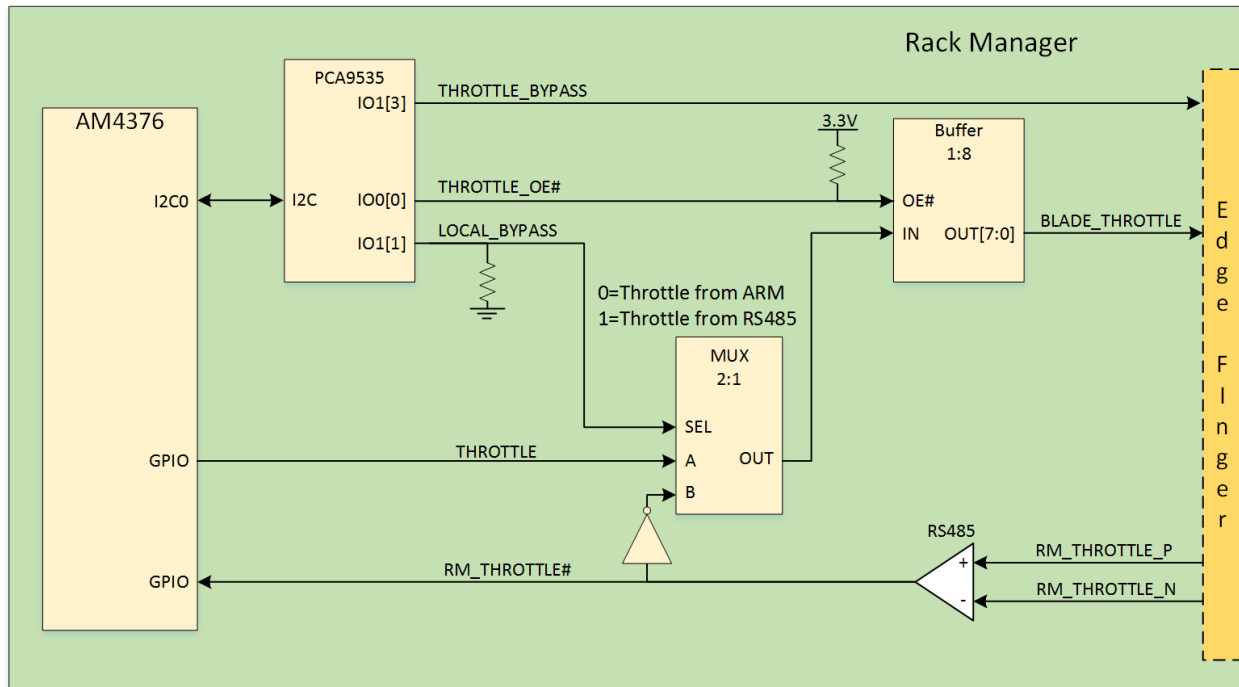


Figure 6. Throttle Block Diagram

3.11.4 LR Select

The Rack Manager shall support a select output to each of the 48 blade slots for enabling power control to the left and right entities within a single slot. The processor shall drive a single GPIO. The board shall contain a buffer to fan out 8 select signals to the PMDU.

3.12 AC Monitor

The Rack Manager shall support AC power monitoring of the 2 AC feeds to the PMDU. The board receives current and voltage sense inputs from the PIB and shall scale them appropriately for the A/D converters in the processor. The processor is responsible for filtering and interpreting the A/D results to determine the rack power.

3.13 Remote Recovery

The Rack Manager contains several features to aid in the remote recovery in the event of a power brownout, processor lockup, or corrupted boot image. These signals are driven from a Row Manager or similar remote device and are cabled to the PMDU or Rack Manager Module (RMM).

3.13.1 Remote Bootstrap

The Rack Manager shall support remote setting of the processor's boot. The signal when asserted shall alter the SYSBOOT setting to direct the processor to switch the boot location from the local ROM or Flash to the network enabling remote recovery in the event of a corrupted or blank boot image. Additional information is contained in Section 3.1.1. The design shall ensure that processor boots from the local ROM when the cable is removed.

3.13.2 Remote Rack Manager ON/OFF

The Rack Manager shall support a remote power on/off control signal input. The signal shall be 5V and when asserted shall disable power to the 12V HSC. The design shall ensure that the HSC remains on when the cable is inserted or removed.

3.13.3 Remote Throttle

The Rack Manager shall support a throttle signal (RM_THROTTLE#) input. When this signal is asserted, the Rack Manager shall assert a throttle output (BLADE_THROTTLE) to all the blades connected to the PMDU. The design shall ensure that throttle output is de-asserted when the cable is removed. The design shall also ensure that throttle control of the blades does not glitch or assert due to insertion of the cable.

3.13.4 Rack Manager Present

The Rack Manager shall support a single present signal (RM_PRESENT#). The signal shall be grounded on the blade to indicate physical presence of the Rack Manager to the RMM.

3.14 Remote AC Power Control

The Rack Manager shall support power control to external AC relays for remote on/off control of rack AC devices. The board shall support four 5V outputs that interface to the PMDU through the edge finger connectors.

3.15 PCB Revision

The Rack Manager shall support reading of a 3-bit PCB revision using GPIOs on the AM4376 processor. Revision shall be set using strapping resistors. The purpose of the ID bits is to communicate to firmware the identity of the Rack Manager in the event that different PCB revisions will require different firmware features to be enabled or disabled. The ID should be incremented with each revision of the PCB.

Table 2. PCB Revision ID

ID	Description
000	EV
001	DV
010	PV

011	TBD
100	TBD
101	TBD
110	TBD
111	TBD

3.16 Board Interface ID

The Rack Manager shall support reading of a 3-bit interface ID using I2C IO expander connecting to the AM4376 processor. The ID bits are received through the PCIe edge finger connector. The purpose of the ID bits is to communicate to firmware the identity of the board mated to the Rack Manager in the event that different interface boards will require different firmware features to be enabled or disabled. ID assignments are shown in Table 3.

Table 3. Board Interface ID

ID	Description
000	Power Interface Board (PMDU)
001	Row PIB Board (RMM)
010	Manufacturing Test Board
011	TBD
100-111	TBD

3.17 AM4376 GPIO Summary

Table 4 shows a summary of the AM4376 GPIO usage.

Table 4. AM4376 GPIO Assignments

Signal	# of Signals	GPIOs Used	I/O	Description
BLADE_PRESENT#	48	48	I	Indicates blade installed in slot
BLADE_ENABLE#	48	48	O	Enable/Disables Blade Power
BLADE_THROTTLE	1	1	O	Enables Blade power throttle
DC_THROTTLE#	1	1	I	Throttle Input
RELAY_CNTL	4	4	O	Turns On/Off Relays in AC Cords
BUFF_OE#	1	1	O	Enables I/O Buffers
ATTENTION_LED	1	1	O	Local LED - TBD
LR_SELECT	1	1	O	Selects Left or Right location in Blade Slot
Total		105		
Available		105		

3.18 I2C Expander (PCA9535)

The Rack Manager supports one I2C Expander for control and reading of selected I/Os. The I/O assignments for each expander are shown in Table 5.

Table 5. PCA9535 I/O Assignments

0x40		PCA9535C		
Port	GPIO	I/O	Signal	Description
1	7	O	Debug_LED 3	0=LED On
1	6	O	Debug_LED 2	0=LED On
1	5	O	Debug_LED 1	0=LED On
1	4	O	Debug_LED 0	0=LED On
1	3	O	THROTTLE_BYPASS	1=Bypass
1	2	I	Board Interface ID 2	See Section 3.16
1	1	I	Board Interface ID 1	See Section 3.16
1	0	I	Board Interface ID 0	See Section 3.16
0	7	I	N/A	N/A
0	6	I	N/A	N/A
0	5	I	N/A	N/A
0	4	I	N/A	N/A
0	3	I	P12VB_GOOD	1=Good
0	2	I	P12VA_GOOD	1=Good
0	1	O	LOCAL_BYPASS	1=Bypass
0	0	O	THROTTLE_OE#	0=Output Enabled

3.19 UARTS

The Rack Manager shall support 3 RS232 UARTS for interfacing to external devices.

- UART 0 – Intended for communication with Management Switches. Utilizes software flow control and does not require hardware flow control signals.
- UART 1 – Intended for communication with the Data Center Digi device. Utilizes full hardware flow control (RTS, CTS, DSR, DTR).
- UART 2 – Intended for debug and future expansion. Utilizes software flow control and does not require hardware flow control signals.

3.20 Power

3.20.1 Power Subsystem

The Rack Manager shall receive 12V through the PCIe connector or a separate power connector. The Rack Manager shall utilize a hot swap circuitry to control in-rush current during hot installation of the

board. Power to the hot swap controller can be disabled externally using the RM_OFF_IN signal. Power rails are generated by a Texas Instruments TPS 65218 Power Management IC (PMIC). A block diagram of the power delivery is shown in Figure 7.

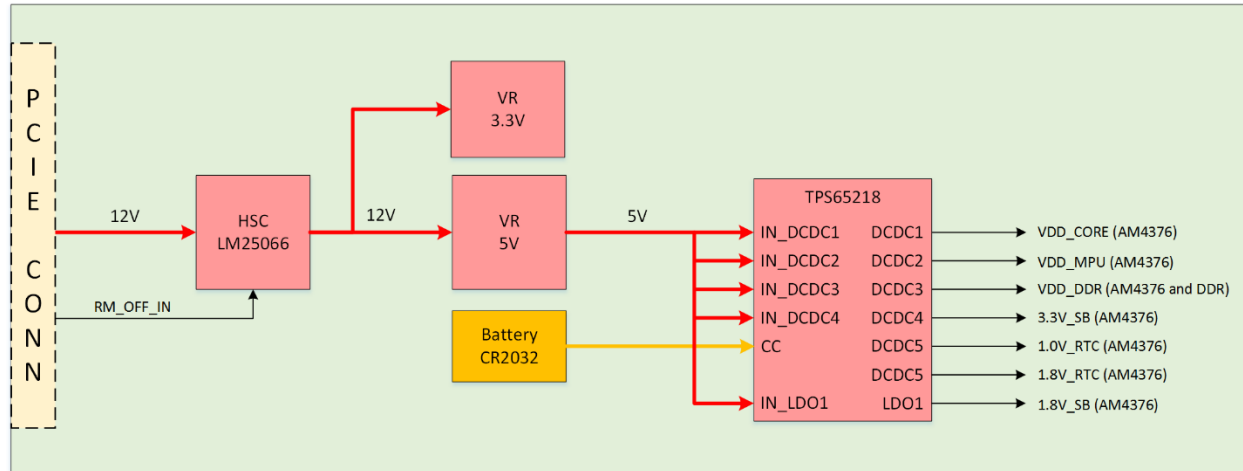


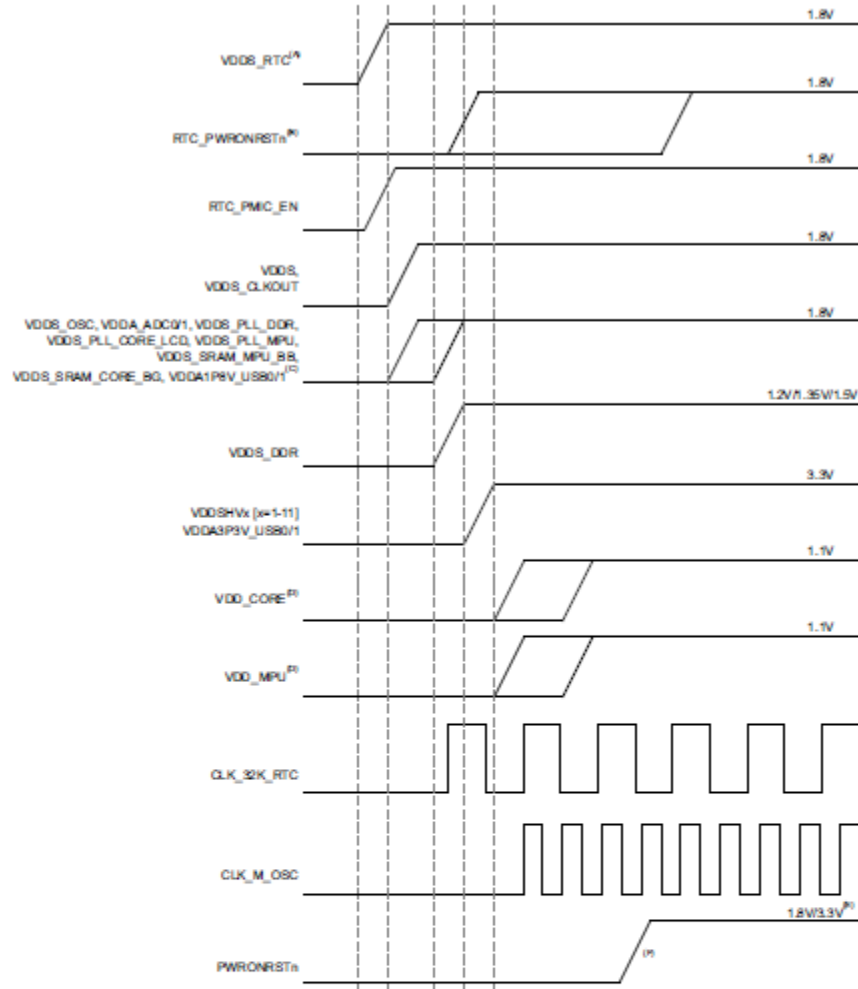
Figure 7. Power Block Diagram

3.20.2 Power-up/down Sequence

The power-up sequencing of all voltage rails, clock and reset must meet AM4376 clock and power sequencing requirements as defined by the device datasheet and referenced in Figure 8. The AM4376 requires the following power sequence during power up:

- 1.8-> 1.35V->3.3V->1.1V, Clock->PWRONRSTn

PWRONRSTn should stay low until all power rails and clock are stable.



- A. The CAP_VDD_RTC terminal operates as an input to the RTC core voltage domain when the internal RTC LDO is disabled by connecting the RTC_KALDO_ENn terminal to VDD_RTC. If the internal RTC LDO is disabled, CAP_VDD_RTC should be sourced from an external 1.1-V power supply. If CAP_VDD_RTC is ramped after VDD_CORE, there might be a small amount of additional leakage current on VDD_CORE. VDD_RTC can be ramped independent of other supplies if RTC_PMIC_EN functionality is not required. If VDD_RTC is ramped after VDD_CORE when internal RTC LDO is enabled, there might be a small amount of leakage current on VDD_CORE.
- B. RTC_PWRONRSTn should be asserted for at least 1 ms and can be released before the 32-kHz clock is stable.
- C. These supplies can be ramped together with VDD_RTC, VDD_RTC_CLKOUT supplies if powered from the same source only. If a USB port is not used, the respective VDDA1P8V_USB may be connected to any 1.8-V power supply and the respective VDDA3P3V_USB terminal may be connected to any 3.3-V power supply. If a system does not have a 3.3-V supply, the VDDA3P3V_USB may be connected to ground.
- D. VDD_MPU and VDD_CORE can be supplied from the same power source if OPPs higher than OPP100 are not used.
- E. PWRONRSTn input voltage thresholds are not dependent on VDDSHV3 voltage and the terminal is not fail-safe. PWRONRSTn can accept 1.8-V or 3.3-V input levels when VDDSHV3 is configured as 3.3 V. However, PWRONRSTn can only accept 1.8 V input levels when VDDSHV3 is configured as 1.8 V. For details on this input terminal, see [Section 5.7](#).
- F. It is required to hold the PWRONRSTn terminal low until all the supplies have ramped and the input clock CLK_M_OSC is stable.

Figure 5-4. Power Sequencing with RTC Feature Enabled, All Dual-Voltage IOs Configured as 3.3 V

Figure 8. Power Up Sequence Diagram

In addition to the power up sequence, it is recommended to limit the maximum slew rate of supplies to be less than $1.0E+5V/s$ to maintain the safe operating range of the internal ESD protection devices. The following diagram shows the supply ramp slew should be more than $18\mu s$ for 1.8V supply.

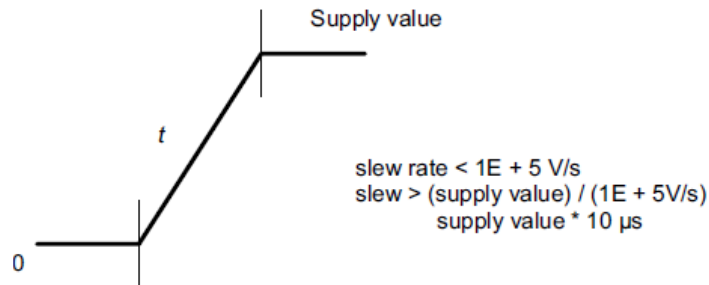


Figure 9. Power Supply Slew Rate Diagram

3.20.3 Grounding and Return

The chassis grounding/return is provided to the board from the front bezel assembly through the alignment and mounting holes that secure the motherboard to PSU. The Rack Manager board ground is also tied to the PSU ground through the edge finger connector. Chassis ground and Logic ground are tied together on the board.

3.20.4 AC-DC Power Monitoring

The Rack Manager receives two power good signals from the AC-DC Converter board indicating the status of AC to DC 12V converters. The power goods are connected to the PCA9535 I2C expander.

3.21 Stackup

The PCB stackup is shown in Figure 10. The board material shall be NPG_170N with OSP surface finish.

To enable visual tracking, the PCB color shall be different for EVT (red), DVT (blue) and PVT (green) builds. PVT build (green) shall be the production PCB color.

10-Layer Board Stack-Up (1.6 mm)				
Layer Name	Layer Description	Material	Layer Thickness (mil)	Copper Weight (oz)
	SOLDER MASK	Solder Mask	0.50	
Signal1	SIGNAL	Copper	1.90	0.5 + 1 (plating)
	PREPREG	FR4	4.00	
GPlane2	GND	Copper	1.20	1.0
	CORE	FR4	4.00	
Signal3	SIGNAL	Copper	1.20	1.0
	PREPREG	FR4	6.50	
GPlane4	GND	Copper	1.20	1.0
	CORE	FR4	4.00	
PPlane5	SIG / PWR	Copper	1.20	1.0
	PREPREG	FR4	12.00	
PPlane6	PWR / SIG	Copper	1.20	1.0
	CORE	FR4	4.00	
GPlane7	GND	Copper	1.20	1.0
	PREPREG	FR4	6.50	
Signal8	SIGNAL	Copper	1.20	1.0
	CORE	FR4	4.00	
GPlane9	GND	Copper	1.20	1.0
	PREPREG	FR4	4.00	
Signal10	SIGNAL	Copper	1.90	0.5 + 1 (plating)
	SOLDER MASK	Solder Mask	0.50	
Overall Board Thickness w/SM			63.40	mils Tol: +/-10%

Figure 10. PCB Stackup

4 Connectors

4.1 PCIe x16 Goldfinger

The board contains one PCIe x16 Edge Finger connector for interfacing signals from the Rack Manager to the Power Interface Board in the MDU. The pinout is shown in [Table 6](#).

Table 6. PCIe x16 Pinout

Pin #	Name	I/O	Voltage	Description
A1	GND	I	0V	GND
A2	GND	I	0V	GND
A3	BLADE_EN_4_N	O	3.3V	Blade power enable output
A4	BLADE_EN_3_N	O	3.3V	Blade power enable output
A5	BLADE_EN_2_N	O	3.3V	Blade power enable output
A6	BLADE_EN_1_N	O	3.3V	Blade power enable output
A7	BLADE_EN_5_N	O	3.3V	Blade power enable output
A8	BLADE_EN_6_N	O	3.3V	Blade power enable output
A9	BLADE_EN_7_N	O	3.3V	Blade power enable output

A10	BLADE_EN_8_N	O	3.3V	Blade power enable output
A11	GND	I	0V	GND
Mechanical Key				
A12	BLADE_EN_12_N	O	3.3V	Blade power enable output
A13	BLADE_EN_11_N	O	3.3V	Blade power enable output
A14	BLADE_EN_10_N	O	3.3V	Blade power enable output
A15	BLADE_EN_9_N	O	3.3V	Blade power enable output
A16	BLADE_EN_13_N	O	3.3V	Blade power enable output
A17	BLADE_EN_14_N	O	3.3V	Blade power enable output
A18	BLADE_EN_15_N	O	3.3V	Blade power enable output
A19	BLADE_EN_16_N	O	3.3V	Blade power enable output
A20	GND	I	0V	GND
A21	BLADE_EN_17_N	O	3.3V	Blade power enable output
A22	BLADE_EN_18_N	O	3.3V	Blade power enable output
A23	BLADE_EN_19_N	O	3.3V	Blade power enable output
A24	BLADE_EN_20_N	O	3.3V	Blade power enable output
A25	BLADE_EN_24_N	O	3.3V	Blade power enable output
A26	BLADE_EN_23_N	O	3.3V	Blade power enable output
A27	BLADE_EN_22_N	O	3.3V	Blade power enable output
A28	BLADE_EN_21_N	O	3.3V	Blade power enable output
A29	GND	I	0V	Ground
A30	BLADE_EN_25_N	O	3.3V	Blade power enable output
A31	BLADE_EN_26_N	O	3.3V	Blade power enable output
A32	BLADE_EN_27_N	O	3.3V	Blade power enable output
A33	BLADE_EN_28_N	O	3.3V	Blade power enable output
A34	BLADE_EN_32_N	O	3.3V	Blade power enable output
A35	BLADE_EN_31_N	O	3.3V	Blade power enable output
A36	BLADE_EN_30_N	O	3.3V	Blade power enable output
A37	BLADE_EN_29_N	O	3.3V	Blade power enable output
A38	GND	I	0V	GND
A39	BLADE_EN_33_N	O	3.3V	Blade power enable output
A40	BLADE_EN_34_N	O	3.3V	Blade power enable output
A41	BLADE_EN_35_N	O	3.3V	Blade power enable output
A42	BLADE_EN_36_N	O	3.3V	Blade power enable output
A43	BLADE_EN_40_N	O	3.3V	Blade power enable output
A44	BLADE_EN_39_N	O	3.3V	Blade power enable output
A45	BLADE_EN_38_N	O	3.3V	Blade power enable output
A46	BLADE_EN_37_N	O	3.3V	Blade power enable output
A47	GND	I	0V	GND
A48	BLADE_EN_41_N	O	3.3V	Blade power enable output
A49	BLADE_EN_42_N	O	3.3V	Blade power enable output

Open Compute Project • Project Olympus Rack Manager Specification

A50	BLADE_EN_43_N	O	3.3V	Blade power enable output
A51	BLADE_EN_44_N	O	3.3V	Blade power enable output
A52	BLADE_EN_48_N	O	3.3V	Blade power enable output
A53	BLADE_EN_47_N	O	3.3V	Blade power enable output
A54	BLADE_EN_46_N	O	3.3V	Blade power enable output
A55	BLADE_EN_45_N	O	3.3V	Blade power enable output
A56	GND	I	0V	Ground
A57	LR_SELECT0	O	3.3V	Left/Right Node Select
A58	LR_SELECT1	O	3.3V	Left/Right Node Select
A59	LR_SELECT2	O	3.3V	Left/Right Node Select
A60	LR_SELECT3	O	3.3V	Left/Right Node Select
A61	LR_SELECT7	O	3.3V	Left/Right Node Select
A62	LR_SELECT6	O	3.3V	Left/Right Node Select
A63	LR_SELECT5	O	3.3V	Left/Right Node Select
A64	LR_SELECT4	O	3.3V	Left/Right Node Select
A65	GND	I	0V	Ground
A66	UART1_TX	O	RS232	UART 1 RTS
A67	UART1_RTS	O	RS232	UART1 DTR
A68	UART1_DTR	O	RS232	UART1 TX
A69	UART1_CTS	I	RS232	UART1 RX
A70	UART1_DSR	I	RS232	UART1 DSR
A71	UART1_RX	I	RS232	UART1 CTS
A72	GND	I	0V	Ground
A73	UART2_RX	I	RS232	UART2 RX
A74	UART2_TX	O	RS232	UART2 TX
A75	GND	I	0V	GND
A76	I2C1_BUFF1_SDA	I/O	3.3V	I2C Data
A77	I2C1_BUFF1_SCL	O	3.3V	I2C Clock
A78	BOARD_INT_ID_0	I	3.3V	Board ID
A79	BOARD_INT_ID_1	I	3.3V	Board ID
A80	BOARD_INT_ID_2	I	3.3V	Board ID
A81	P12V7A_GOOD	I	3.3V	P12VA Power Good
A82	P12V7B_GOOD	I	3.3V	P12VB Power Good
B1	GND	I	0V	GND
B2	GND	I	0V	GND
B3	BLADE_PRESENT_4_N	I	3.3V	Blade present
B4	BLADE_PRESENT_3_N	I	3.3V	Blade present
B5	BLADE_PRESENT_2_N	I	3.3V	Blade present
B6	BLADE_PRESENT_1_N	I	3.3V	Blade present
B7	BLADE_PRESENT_5_N	I	3.3V	Blade present
B8	BLADE_PRESENT_6_N	I	3.3V	Blade present

B9	BLADE_PRESENT_7_N	I	3.3V	Blade present
B10	BLADE_PRESENT_8_N	I	3.3V	Blade present
B11	GND	I	0V	GND
Mechanical Key				
B12	BLADE_PRESENT_12_N	I	3.3V	Blade present
B13	BLADE_PRESENT_11_N	I	3.3V	Blade present
B14	BLADE_PRESENT_10_N	I	3.3V	Blade present
B15	BLADE_PRESENT_9_N	I	3.3V	Blade present
B16	BLADE_PRESENT_13_N	I	3.3V	Blade present
B17	BLADE_PRESENT_14_N	I	3.3V	Blade present
B18	BLADE_PRESENT_15_N	I	3.3V	Blade present
B19	BLADE_PRESENT_16_N	I	3.3V	Blade present
B20	GND	I	0V	GND
B21	BLADE_PRESENT_17_N	I	3.3V	Blade present
B22	BLADE_PRESENT_18_N	I	3.3V	Blade present
B23	BLADE_PRESENT_19_N	I	3.3V	Blade present
B24	BLADE_PRESENT_20_N	I	3.3V	Blade present
B25	BLADE_PRESENT_24_N	I	3.3V	Blade present
B26	BLADE_PRESENT_23_N	I	3.3V	Blade present
B27	BLADE_PRESENT_22_N	I	3.3V	Blade present
B28	BLADE_PRESENT_21_N	I	3.3V	Blade present
B29	GND	I	0V	Ground
B30	BLADE_PRESENT_25_N	I	3.3V	Blade present
B31	BLADE_PRESENT_26_N	I	3.3V	Blade present
B32	BLADE_PRESENT_27_N	I	3.3V	Blade present
B33	BLADE_PRESENT_28_N	I	3.3V	Blade present
B34	BLADE_PRESENT_32_N	I	3.3V	Blade present
B35	BLADE_PRESENT_31_N	I	3.3V	Blade present
B36	BLADE_PRESENT_30_N	I	3.3V	Blade present
B37	BLADE_PRESENT_29_N	I	3.3V	Blade present
B38	GND	I	0V	GND
B39	BLADE_PRESENT_33_N	I	3.3V	Blade present
B40	BLADE_PRESENT_34_N	I	3.3V	Blade present
B41	BLADE_PRESENT_35_N	I	3.3V	Blade present
B42	BLADE_PRESENT_36_N	I	3.3V	Blade present
B43	BLADE_PRESENT_40_N	I	3.3V	Blade present
B44	BLADE_PRESENT_39_N	I	3.3V	Blade present
B45	BLADE_PRESENT_38_N	I	3.3V	Blade present
B46	BLADE_PRESENT_37_N	I	3.3V	Blade present
B47	GND	I	0V	GND
B48	BLADE_PRESENT_41_N	I	3.3V	Blade power enable output

Open Compute Project • Project Olympus Rack Manager Specification

B49	BLADE_PRESENT_42_N	I	3.3V	Blade power enable output
B50	BLADE_PRESENT_43_N	I	3.3V	Blade power enable output
B51	BLADE_PRESENT_44_N	I	3.3V	Blade power enable output
B52	BLADE_PRESENT_48_N	I	3.3V	Blade power enable output
B53	BLADE_PRESENT_47_N	I	3.3V	Blade power enable output
B54	BLADE_PRESENT_46_N	I	3.3V	Blade power enable output
B55	BLADE_PRESENT_45_N	I	3.3V	Blade power enable output
B56	GND	I	0V	Ground
B57	BLADE_19TO24_THROTTLE	O	3.3V	Blade Throttle
B58	BLADE_13TO18_THROTTLE	O	3.3V	Blade Throttle
B59	BLADE_7TO12_THROTTLE	O	3.3V	Blade Throttle
B60	BLADE_1TO6_THROTTLE	O	3.3V	Blade Throttle
B61	BLADE_25TO30_THROTTLE	O	3.3V	Blade Throttle
B62	BLADE_31TO36_THROTTLE	O	3.3V	Blade Throttle
B63	BLADE_37TO42_THROTTLE	O	3.3V	Blade Throttle
B64	BLADE_43TO48_THROTTLE	O	3.3V	Blade Throttle
B65	GND	I	0V	Ground
B66	RELAY_CNTL_3	O	5V	0 = AC Power enabled to load 1 = AC Power disabled to load
B67	RELAY_CNTL_2	O	5V	0 = AC Power enabled to load 1 = AC Power disabled to load
B68	RELAY_CNTL_1	O	5V	0 = AC Power enabled to load 1 = AC Power disabled to load
B69	RELAY_CNTL_0	O	5V	0 = AC Power enabled to load 1 = AC Power disabled to load
B70	GND	I	0V	GND
B71	UART0_RX	I	RS232	UART0 RX
B72	UART0_TX	O	RS232	UART0 TX
B73	RM_PRESENT#	O	3.3V	Indicates RM is installed.
B74	RM_OFF_IN	I	5V	Hot Swap Controller disable
B75	THROTTLE_BYPASS	O	3.3V	Enables throttle to bypass Rack Manager
B76	GND	I	0V	I2C Data
B77	RM_THROTTLE_RS485_P	I	RS485	RM Throttle RS485 Input
B78	RM_THROTTLE_RS485_N	I	RS485	RM Throttle RS485 Input
B79	GND	I	0V	GND
B80	BOOTSTRAP_RS485_P	I	RS485	Bootstrap RS485 Input
B81	BOOTSTRAP_RS485_N	I	RS485	Bootstrap RS485 Input
B82	GND	I	0V	GND

4.2 PCIe x8 Goldfinger

The board contains one PCIe x8 Edge Finger connector for interfacing signals from the Rack Manager to the Power Interface Board in the PMDU. The pinout is shown in Table 7.

Table 7. PCIe x8 Pinout

Pin #	Name	I/O	Voltage	Description
A1	GND	I	0V	GND
A2	GND	I	0V	GND
A3	GND	I	0V	GND
A4	GND	I	0V	GND
A5	GND	I	0V	GND
A6	GND	I	0V	GND
A7	NC			No Connect
A8	P3V3	O	3.3V	3.3V Power Output
A9	P3V3	O	3.3V	3.3V Power Output
A10	P3V3	O	3.3V	3.3V Power Output
A11	P3V3	O	3.3V	3.3V Power Output
Mechanical Key				
A12	P5V	O	5V	5V Power Output
A13	P5V	O	5V	5V Power Output
A14	P5V	O	5V	5V Power Output
A15	NC	O		No Connect
A16	AGND	I	0V	Analog GND
A17	AGND	I	0V	Analog GND
A18	AC_SOURCE2_N2_VS	I	AC	AC Voltage Sense - Neutral
A19	AC_SOURCE2_S_VS	I	AC	AC Voltage Sense - Line
A20	AGND	I	0V	Analog GND
A21	AGND	I	0V	Analog GND
A22	AC_SOURCE2_S_CS2	I	AC	AC Current Sense - Line
A23	AC_SOURCE2_S_CS1	I	AC	AC Current Sense - Line
A24	AGND	I	0V	Analog GND
A25	AGND	I	0V	Analog GND
A26	AC_SOURCE2_N1_VS	I	AC	AC Voltage Sense - Neutral
A27	AC_SOURCE2_R_VS	I	AC	AC Voltage Sense - Line
A28	AGND	I	0V	Analog GND
A29	AGND	I	0V	Analog GND
A30	AC_SOURCE2_T_CS2	I	AC	AC Current Sense - Line
A31	AC_SOURCE2_T_CS1	I	AC	AC Current Sense - Line

Open Compute Project • Project Olympus Rack Manager Specification

A32	AGND	I	0V	Analog GND
A33	AGND	I	0V	Analog GND
A34	AC_SOURCE2_N3_VS	I	AC	AC Voltage Sense - Neutral
A35	AC_SOURCE2_T_VS	I	AC	AC Voltage Sense - Line
A36	AGND	I	0V	Analog GND
A37	AGND	I	0V	Analog GND
A38	AC_SOURCE2_R_CS2	I	0V	AC Current Sense - Line
A39	AC_SOURCE2_R_CS1	I	0V	AC Current Sense - Line
A40	GND	I	0V	GND
A41	GND	I	0V	GND
A42	GND	I	0V	GND
A43	GND	I	0V	GND
A44	GND	I	0V	GND
A45	GND	I	0V	GND
A46	GND	I	0V	GND
A47	GND	I	0V	GND
A48	GND	I	0V	GND
A49	GND	I	0V	GND
B1	P12V_IN	I	12V	12V Power Input
B2	P12V_IN	I	12V	12V Power Input
B3	P12V_IN	I	12V	12V Power Input
B4	P12V_IN	I	12V	12V Power Input
B5	P12V_IN	I	12V	12V Power Input
B6	NC			No Connect
B7	GND	I	0V	GND
B8	GND	I	0V	GND
B9	GND	I	0V	GND
B10	GND	I	0V	GND
B11	GND	I	0V	GND
Mechanical Key				
B12	GND	I	0V	GND
B13	GND	I	0V	GND
B14	GND	I	0V	GND
B15	GND	I	0V	GND
B16	GND	O	AC	GND
B17	GND	O	AC	GND
B18	AGND	I	0V	Analog GND
B19	AGND	I	0V	Analog GND
B20	AC_SOURCE1_N2_VS	I	AC	AC Voltage Sense - Neutral
B21	AC_SOURCE1_S_VS	I	AC	AC Voltage Sense - Line
B22	AGND	I	0V	Analog GND

B23	AGND	I	0V	Analog GND
B24	AC_SOURCE1_S_CS2	I	AC	AC Current Sense - Line
B25	AC_SOURCE1_S_CS1	I	AC	AC Current Sense - Line
B26	AGND	I	0V	Analog GND
B27	AGND	I	0V	Analog GND
B28	AC_SOURCE1_N1_VS	I	AC	AC Voltage Sense - Neutral
B29	AC_SOURCE1_R_VS	I	AC	AC Voltage Sense - Line
B30	AGND	I	0V	Analog GND
B31	AGND	I	0V	Analog GND
B32	AC_SOURCE1_T_CS2	I	AC	AC Current Sense - Line
B33	AC_SOURCE1_T_CS1	I	AC	AC Current Sense - Line
B34	AGND	I	0V	Analog GND
B35	AGND	I	0V	Analog GND
B36	AC_SOURCE1_N3_VS	I	AC	AC Voltage Sense - Neutral
B37	AC_SOURCE1_T_VS	I	AC	AC Voltage Sense - Line
B38	AGND	I	0V	Analog GND
B39	AGND	I	0V	Analog GND
B40	AC_SOURCE1_R_CS2	I	0V	AC Current Sense - Line
B41	AC_SOURCE1_R_CS1	I	0V	AC Current Sense - Line
B42	GND	I	0V	GND
B43	GND	I	0V	GND
B44	GND	I	0V	GND
B45	GND	I	0V	GND
B46	GND	I	0V	GND
B47	GND	I	0V	GND
B48	GND	I	0V	GND
B49	GND	I	0V	GND

4.3 RJ45 GbE Connectors

The Rack Manager shall contain two RJ45 connectors located on the bulkhead of the assembly for cabling 1GbE. The pinout for the connector is shown in Table 8.

Table 8. RJ45 GbE Pinout

Pin #	Signal	I/O	Description
1	TX_D1+	O	Transmit Data +
2	TX_D1-	O	Transmit Data -
3	RX_D2+	I	Receive Data +
4	BI_D3+	I/O	Bi-directional Data +
5	BI_D3-	I/O	Bi-directional Data -

6	RX_D2-	I	Receive Data -
7	BI_D4+	I/O	Bi-directional Data +
8	BI_D4-	I/O	Bi-directional Data -

4.4 I2C Debug Header

The board shall include a 3 pin I2C header on all I2C busses. This is a standard 100mil pitch 3-pin header. The pinout should be compatible with standard I2C debug solutions such as Beagle and Aardvark.

5 Mechanical Specifications

This specification describes key mechanical elements of the M.2 storage board.

5.1 Mechanical Dimensions

Mechanical Dimensions are shown in Figure 11.

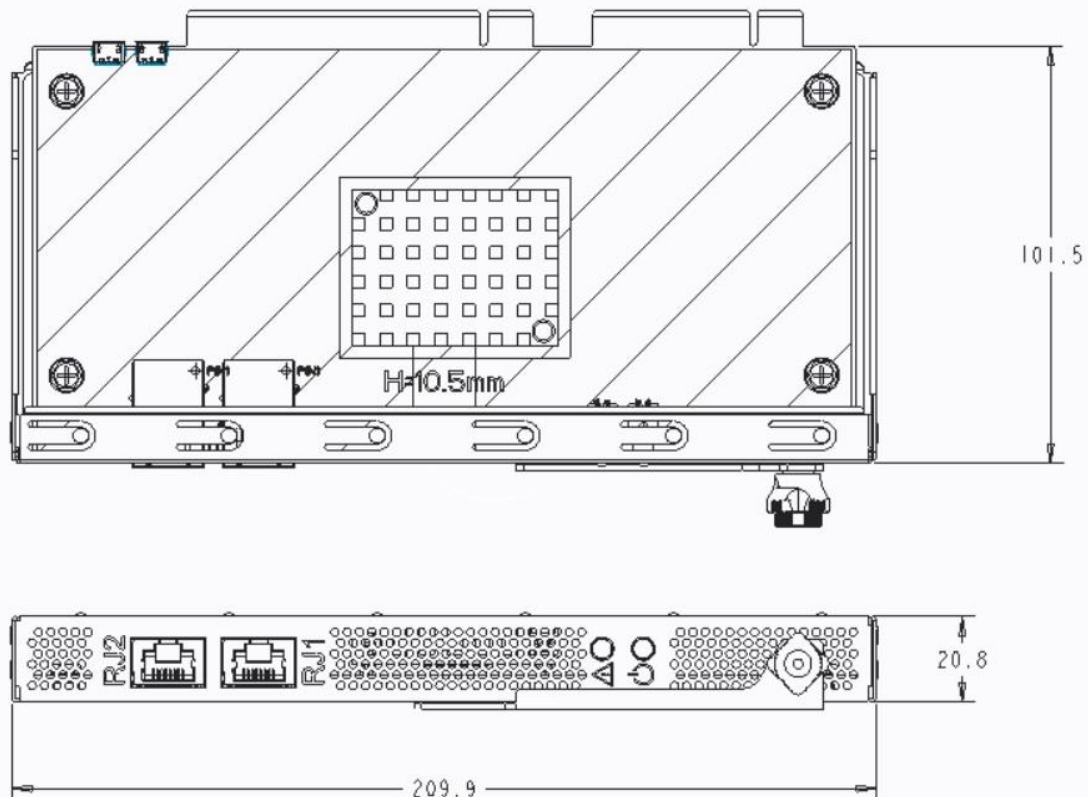


Figure 11. Mechanical Dimensions

5.2 Thermal

The solution must operate in a 60 degrees Centigrade environment and must be passively cooled.